	Material Comp © Copyright 2005. I international and Par	PC, Bannockt	ourn, Illinois. A	Il rights reserved untions.	nder both	This docume level parts, t	ent is a declara he declaration	ation c i encoi	of the substances mpasses all lowe	within th r level ma	e manufactur aterials for w	er listed it hich the m	em. Note: if aanufacturer l	the item is an as	ssembly with lowe responsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information				
Supplier	· Information														
Company name* Cor				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2025-06-06			
Contact Na	ame	Title - Contact			]	Phone - Contact*					Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	d Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*					
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturin		uring Site	Weight*		UOM	Unit Type		
	1N52421		3	12V 500MW 5% ZENER DO35			2025-06-06			CN2		1	109.66989	mg	Each
Aanufao	cturing Proccess Informa	tion		1			1					1		I	
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Bod		Body Temperature Max Time at Peak		Temperature Number of		r of Reflow Cy	cles	
	Matte Tin (Sn) - annealed		U Alloy NA			0 C		<b>30</b> seco		secon	ds 3				
Comments															
or more i	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (		dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of				
<b>RoHS Declaration *</b> 4 - Item(s	) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to ha			ice drop-dowi	n. This will display the signature area. Digital	ly sign the declaration (if required by the				
Supplier Digital Signature R	astislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
CSS Wire	75.0	mg	Supplier	Iron (Fe)	7439-89-6		63.75	mg
			Supplier	Copper (Cu)	7440-50-8		11.25	mg
Die	0.024358	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			Supplier	Silver (Ag)	7440-22-4		0.0115	mg
			Supplier	Silicon (Si)	7440-21-3		0.0127	mg
			В	Nickel (Ni)	7440-02-0		0.0001	mg
Dumet Wire	8.5	mg	Supplier	Manganese (Mn)	7439-96-5		0.085	mg
			Supplier	Silicon (Si)	7440-21-3		0.0595	mg
			В	Nickel (Ni)	7440-02-0		2.6775	mg
			Supplier	Iron (Fe)	7439-89-6		3.6805	mg
			Supplier	Copper (Cu)	7440-50-8		1.9975	mg
Glass Encapsulation	23.5	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		0.705	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	14.382	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.0118	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		0.8813	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.52	mg
Marking Ink	0.01953	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.004	mg
			Supplier	Formaldehyde, polymer with 4,4-(1- methylethylidene)bisphenol	25085-75-0		0.0052	mg
			Supplier	Proprietary	Proprietary Data		0.0009	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.001	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0013	mg
			Supplier	Diethylene glycol 2-ethyhexyl-ether	1559-36-0		0.0025	mg
			Supplier	Amino Resin	68002-20-0		0.0033	mg
			Supplier	2,2,4-Trimethyl-1,3-pentanediol di is Obutyrate	6846-50-0		0.0013	mg
Plating	2.626	mg	Supplier	Tin (Sn)	7440-31-5		2.626	mg